



PCN: V11-007-32002150-0B

Product Change Notice

Issue Date: 9 June 2011

Change Type:

Change in molding equipment

Parts Affected:

HCPL-0900	HCPL-092J	HCPL-9000	HCPL-902J	QCPL-903J
HCPL-090J	HCPL-0930	HCPL-900J	HCPL-9030	
HCPL-091J	HCPL-0931	HCPL-901J	HCPL-9031	

All associated options and special part numbers will also be affected. See Appendix for full part number list.

Description and Extent of Change:

Change in molding equipment for package assembly, and Standard DIP and Narrowbody SOIC-16 package dimension (see Appendix II)

Reasons for Change:

Avago manufacturing has upgraded molding equipment for package assembly of digital isolator products. This change does not affect the electrical parameters of the parts.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

The device specification will remain unchanged, which ensures product electrical performance is the same. Appropriate electrical characterization and reliability qualification have been performed on representative products to ensure normal parametric distribution, consistent electrical performance, and reliability.

Effective Date of Change:

Product shipment using this change begins with date-code starting from 1114 (yyww). However, timing of shipment of changed part will vary by part number depending on customer demand and inventory levels.

Qualification Data:

Qualification data has been generated and approved.

These changes have been reviewed and approved by Avago Technologies engineers and managers per Avago Technologies procedure: Change Control and Customer Notification, A-5962-6052-80. Please contact your Avago Technologies field sales engineer or Contact Center (<http://www.avagotech.com/contact/>) for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.

APPENDIX

Base Part Number	Part Number with Option
HCPL-0900	HCPL-0900 HCPL-0900-500 HCPL-0900-000E HCPL-0900-500E
HCPL-090J	HCPL-090J HCPL-090J-500 HCPL-090J-000E HCPL-090J-500E
HCPL-091J	HCPL-091J HCPL-091J-500 HCPL-091J-000E HCPL-091J-500E
HCPL-092J	HCPL-092J HCPL-092J-500 HCPL-092J-000E HCPL-092J-500E
HCPL-0930	HCPL-0930 HCPL-0930-500 HCPL-0930-000E HCPL-0930-500E
HCPL-0931	HCPL-0931 HCPL-0931-500 HCPL-0931-000E HCPL-0931-500E
HCPL-9000	HCPL-9000 HCPL-9000-300 HCPL-9000-500 HCPL-9000-000E HCPL-9000-300E HCPL-9000-500E
HCPL-900J	HCPL-900J HCPL-900J-500 HCPL-900J-000E HCPL-900J-500E

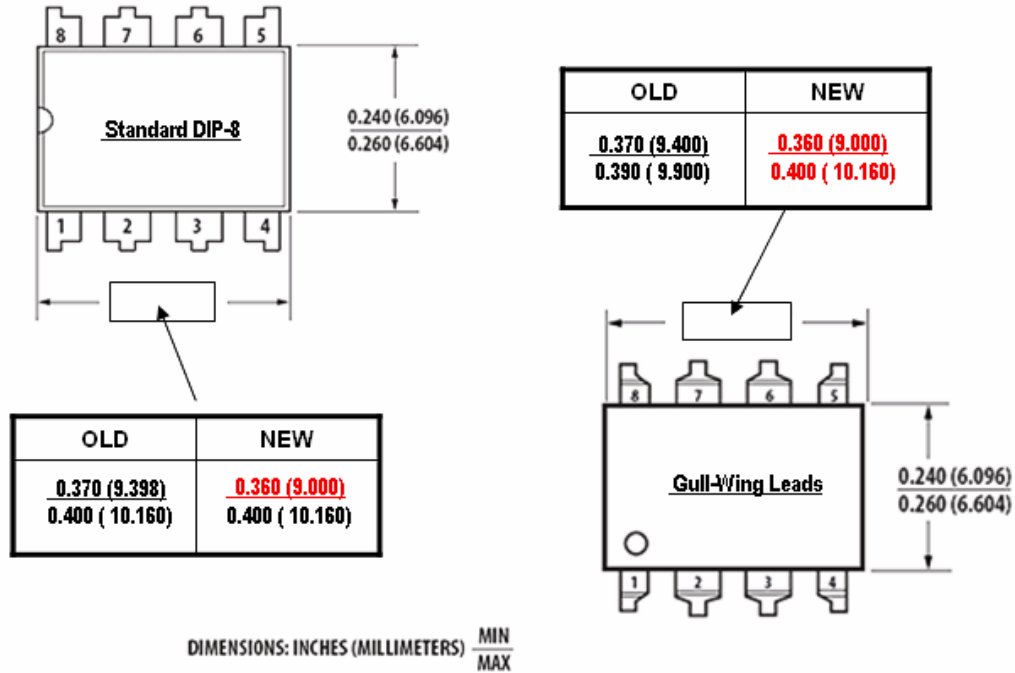
Base Part Number	Part Number with Option
HCPL-901J	HCPL-901J HCPL-901J-500 HCPL-901J-000E HCPL-901J-500E
HCPL-902J	HCPL-902J HCPL-902J-500 HCPL-902J-000E HCPL-902J-500E
HCPL-9030	HCPL-9030 HCPL-9030-300 HCPL-9030-500 HCPL-9030-000E HCPL-9030-300E HCPL-9030-500E
HCPL-9031	HCPL-9031 HCPL-9031-300 HCPL-9031-500 HCPL-9031-000E HCPL-9031-300E HCPL-9031-500E
QCPL-903J	QCPL-903J-000E QCPL-903J-500E

APPENDIX II

Revised package dimension for Standard DIP and Narrow-body SOIC -16

Package Outline Drawings

HCPL-9000, HCPL-9030 and HCPL-9031 Standard DIP Package / Gull Wing Surface Mount Option



HCPL-090J, HCPL-091J and HCPL-092J Narrow Body SOIC-16 Package

